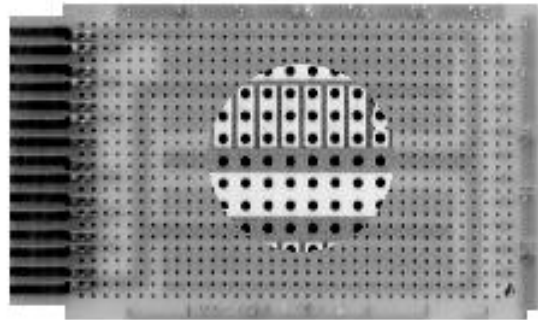


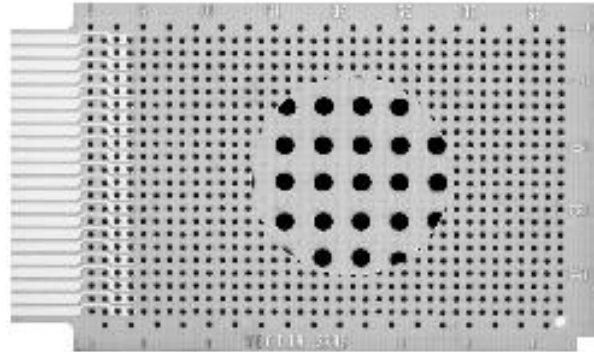
3797-2 2.73" x 4.5"

Circuit Pattern:	3-Hole Solder Pad	
Contacts:	15/30 @ .156" Ctrs, Ni/Gold	<ul style="list-style-type: none"> • 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads • All pad and bus surfaces solder-coated for user convenience • Convenient, easy-to-read hole marking legend on wiring side • Layout paper and instructions included
Width/Thick:	4.50"/.062"	
Height:	2.73"	
16-Pin DIP Capacity:	4	
Material:	CEM-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Solder Connector:	R630	
Extender:	3690-10	
Rec. Card Cage:	Series 12	
Hole Diameter:	.042"	



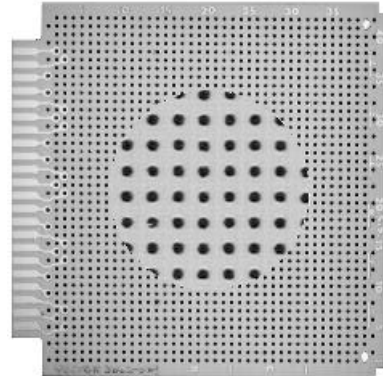
3795 2.73" x 4.5"

Circuit Pattern:	Contacts Only	<ul style="list-style-type: none"> • Unrestricted component placement over entire board surface • Accepts virtually any type of component • Row and column legend provided • Layout paper and instructions included
Contacts:	22/44 @ .156" Ctrs, Ni/Gold	
Width/Thick:	4.50"/.062"	
Height:	2.73"	
16-Pin DIP Capacity:	15	
Material:	CEM-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Solder Connector:	R630	
Extender:	3690-8	
Rec. Card Cage:	Series 12	
Wire-Wrap Connector:	R644-2	
Hole Diameter:	.042"	



3662-5 4.5" x 4.5"

Circuit Pattern:	Contacts Only	<ul style="list-style-type: none"> • 22 numbered edge contacts on front side; 21 plus grounding contact on reverse side • Bare board provides for unrestricted component placement over entire board surface • Hole marking legend on both sides of board • Layout paper and instructions included
Contacts:	22/44 @ .156" Ctrs, Ni/Gold	
Width/Thick:	4.50"/.062"	
Height:	4.50"	
16-Pin DIP Capacity:	40	
Material:	CEM-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Solder Connector:	R644	
Extender:	3690	
Rec. Card Cage:	Series 13	
Wire-Wrap Connector:	R644-3	
Hole Diameter:	.042"	



Circuit Pattern:	Zig-Zag Buses	<ul style="list-style-type: none"> • 3-hole solder pad pattern on wiring side; ground plane on component side with 0.085" diameter, clearance areas around holes • 3-hole solder pads (0.028" x 0.080") for interconnecting multiple component leads • To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately • Layout paper and instructions included • Row and column legend provided • Ground Plane/3-Hole Solder Pad with Zig-Zag Buses
Contacts:	22/44 @ .156" Ctrs, Ni/Gold	
Width/Thick:	4.50"/.062"	
Height:	4.50"	
16-Pin DIP Capacity:	8	
Material:	CEM-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Solder Connector:	R644	
Extender:	3690	
Rec. Card Cage:	Series 13	
Wire-Wrap Connector:	R644-3	
Hole Diameter:	.042"	

